

bq3287E/bq3287EA

Real-Time Clock (RTC) Module

Features

- ➤ Direct clock/calendar replacement for IBM®AT-compatible computers and other applications
- ➤ Functionally compatible with the DS1287/DS1287A and MC146818A/MC146818B
- ➤ 242 bytes of general nonvolatile storage
- ➤ Provides a 32.768kHz output for power management
- System wake-up capability alarm interrupt active in battery-backup mode
- ➤ Integral lithium cell and crystal
- ➤ 160 ns cycle time allows fast bus operation
- ➤ 14 bytes for clock/calendar and control
- ➤ Time of day in seconds, minutes, and hours
 - 12- or 24-hour format
 - Optional daylight saving adjustment

- ➤ Calendar in day of the week, day of the month, months, and years with automatic leap-year adjustment
- ➤ Programmable square wave output
- ➤ Three individually maskable interrupt event flags:
 - Periodic rates from 122µs to 500ms
 - Time-of-day alarm once per second to once per day
 - End-of-clock update cycle
- ➤ Better than one minute per month clock accuracy

General Description

The CMOS bq3287E/bq3287EA is a low-power microprocessor peripheral providing a time-of-day clock and 100-year calendar with alarm features and battery operation. Other features include three maskable interrupt sources, square-wave output, and 242 bytes of general nonvolatile storage. A 32.768kHz output is available for sustaining power-management activities. Wake-up capability is pro-

vided by an alarm interrupt, which is active in battery-backup mode. The bq3287EA version is identical to the bq3287E, with the addition of the RAM clear input.

The bq3287E is a fully compatible real-time clock for IBM AT-compatible computers and other applications. The bq3287E write-protects the clock, calendar, and storage registers during power failure. The integral backup energy source then maintains data and operates the clock and calendar.

As shipped from Benchmarq, the real time clock is turned off to maximize battery capacity for in-system operation.

The bq3287E is functionally equivalent to the bq3285E, except the battery (16,20) and crystal pins (2,3) are not accessible. These pins are connected internally to a coin cell and quartz crystal. The coin cell is sized to provide 10 years of data retention and clock operation in the absence of power. For a complete description of features, operating conditions, electrical characteristics, bus timing, and pin descriptions, see the bq3285E data sheet.

Pin Connections

		1			
1	24	□ vcc			
2	23	□sQW			
3	22	□ EXTRAM			
4	21	□ NC/RCL			
5	20	□ NC			
6	19	□ ĪNT			
7	18	□ RST			
8	17	□ DS			
9	16	□ NC			
10	15	□ R/W			
11	14	□AS			
12	13	□cs			
		J			
24-Pin DIP Module					
	PN32	87E1.eps			
	3 4 5 6 7 8 9 10 11 12	2 23 3 22 4 21 5 20 6 19 7 18 8 17 9 16 10 15 11 14 12 13			

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Pin Names

AD0-AD7	Multiplex address/data input/output	$\overline{\text{RST}}$	Reset input
MOT		SQW	Square wave output
CS	Chip select input	EXTRAM	Extended RAM enable
AS	Address strobe input	NC	No connect
DS	Data strobe input	RCL	RAM clear input (bq3287EA only)
R/\overline{W}	Read/write input	V_{CC}	+5V supply
ĪNT	Interrupt request output	V_{SS}	Ground

bq3287E/bq3287EA

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit	Conditions
Vcc	DC voltage applied on V_{CC} relative to V_{SS}	-0.3 to 7.0	V	
V_{T}	DC voltage applied on any pin excluding V_{CC} relative to V_{SS}	-0.3 to 7.0	V	$V_T \leq V_{CC} + 0.3$
T _{OPR}	Operating temperature	0 to +70	°C	Commercial
T _{STG}	Storage temperature	-40 to +70	°C	Commercial
T _{BIAS}	Temperature under bias	-10 to +70	°C	Commercial
T _{SOLDER}	Soldering temperature	260	°C	For 10 seconds

Note:

Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

Recommended DC Operating Conditions (TA = TOPR)

Symbol	Parameter	Minimum	Typical	Maximum	Unit
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{SS}	Supply voltage	0	0	0	V
V_{IL}	Input low voltage	-0.3	-	0.8	V
V_{IH}	Input high voltage	2.2	-	$V_{CC} + 0.3$	V

Note:

Typical values indicate operation at T_A = 25°C.

DC Electrical Characteristics (TA = TOPR, VCC = 5V ± 10%)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Conditions/Notes
I_{LI}	Input leakage current	-	-	± 1	μΑ	$V_{IN} = V_{SS}$ to V_{CC}
I_{LO}	Output leakage current	-	-	± 1	μΑ	AD ₀ –AD ₇ , INT and SQW in high impedance
V _{OH}	Output high voltage	2.4	-	-	V	$I_{OH} = -1.0 \text{ mA}$
Vol	Output low voltage	-	-	0.4	V	$I_{OL} = 4.0 \text{ mA}$
I _{CC}	Operating supply current	-	7	15	mA	Min. cycle, duty = 100%, $I_{OH} = 0$ mA, $I_{OL} = 0$ mA
V _{SO}	Supply switch-over voltage	-	3.0	-	V	
V _{PFD}	Power-fail-detect voltage	4.0	4.17	4.35	V	
I_{RCL}	Input current when $\overline{RCL} = V_{SS}$	-	-	185	μΑ	Internal 30K pull-up (bq3287EA only)
I _{MOTH}	Input current when MOT = V _{CC}	-	-	-185	μΑ	Internal 30K pull-down
I _{XTRAM}	Input current when EXTRAM = V _{CC}	-	-	-185	μΑ	Internal 30K pull-down

Note:

Typical values indicate operation at $T_A = 25$ °C, $V_{CC} = 5V$.

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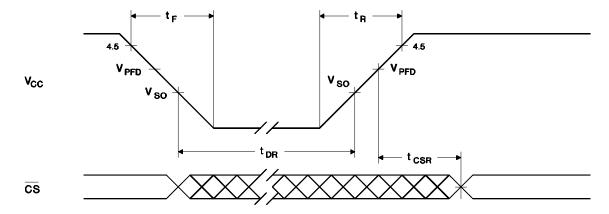
Power-Down/Power-Up Timing (TA = TOPR)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Conditions
t_{F}	V _{CC} slew from 4.5V to 0V	300	-	-	μs	
t_R	V _{CC} slew from 0V to 4.5V	100	-	-	μs	
tcsr	$\overline{\text{CS}}$ at V_{IH} after power-up	20	-	200	ms	Internal write-protection period after V_{CC} passes V_{PFD} on power-up.
t _{DR}	Data-retention and time- keeping time	10	-	-	years	$T_A = 25$ °C.

Note: Clock accuracy is better than $\pm~1$ minute per month at 25°C for the period of t_{DR} .

 ${\bf Caution:} \quad {\bf Negative \ under shoots \ below \ the \ absolute \ maximum \ rating \ of \ -0.3V \ in \ battery-backup \ mode \\ may \ affect \ data \ integrity.}$

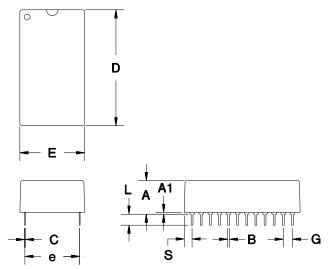
Power-Down/Power-Up Timing



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24-Pin MT (T-type module)



24-Pin MT (T-Type Module)

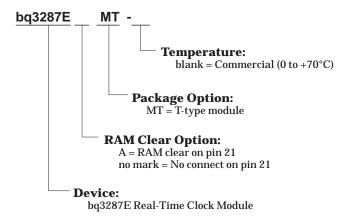
	Inc	hes	Millin	neters		
Dimension	Min. Max.		Min.	Max.		
A	0.360	0.390	9.14	9.91		
A1	0.015	-	0.38	-		
В	0.015	0.022	0.38	0.56		
С	0.008	0.013	0.20	0.33		
D	1.320	1.335	33.53	33.91		
E	0.710	0.740	18.03	18.80		
e	0.590	0.620	14.99	15.75		
G	0.090	0.110	2.29	2.79		
L	0.110	0.130	2.79	3.30		
S	0.100	0.120	2.54	3.05		

Data Sheet Revision History

Change No.	Page No.	Description	Nature of Change
1	8	Register C, bit 2	Was 0; is na (not affected)
2	2	I_{RCL} max. was 275; is now 185. Pull-down = 30K.	Value change
2	2	I _{XTRAM} max. was -75; is now -185.	Value change

Change 1 = Apr. 1994 B "Final" changes from Dec. 1993 A "Preliminary." Change 2 = Sept. 1996 C changes from April 1994 B. **Notes:**

Ordering Information



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